

Product / Process Change Notification



N° 2014-058-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Move of assembly location to Amkor and implementation of AMKOR's standard BoM for DSO-8 non-exposed pad products and additionally move of wafer fab and wafer test location to Kulim for TLE8250G and TLE8250GVIO

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **08. August 2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

In case the customer rejects this PCN this PCN shall be considered a product discontinuation notice (PD).

Infineon Technologies AG
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Arunjai Mittal
Registered Office: Neubiberg
Commercial Register: München HRB 126492

Product / Process Change Notification



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► **Products affected:**

Please refer to 1_cip14058_a

► **Detailed Change Information:**

Subject: Move of assembly location to Amkor and implementation of AMKOR's standard BoM for DSO-8 non-exposed pad products and additionally move of wafer fab and wafer test location to Kulim for TLE8250G and TLE8250GVIO.

Reason: Due to continuously raising demand for Infineon automotive products we are going to introduce the package subcontractor Amkor Technologies, Philippines as a new assembly location.

Description:	<u>Old</u>	<u>New</u>
Assembly location	<ul style="list-style-type: none"> Infineon Technologies, Malacca, Malaysia 	<ul style="list-style-type: none"> Amkor Philippines
Bill of Material (BoM)	<ul style="list-style-type: none"> Infineon robust-green BoM 	<ul style="list-style-type: none"> Amkor automotive green standard BoM
MSL	<ul style="list-style-type: none"> 3 	<ul style="list-style-type: none"> 2a
Wafer fab location (only for TLE8250G and TLE8250GVIO)	<ul style="list-style-type: none"> Infineon Technologies AG, Regensburg, Germany 	<ul style="list-style-type: none"> Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia
Wafer test location (only for TLE8250G and TLE8250GVIO)	<ul style="list-style-type: none"> Infineon Technologies AG, Regensburg, Germany 	<ul style="list-style-type: none"> Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia

► **Product Identification:**

- New SP/OPN number
- For Amkor packages: mold location number on package backside.

► **Impact of Change:**

Amkor Philippines, using state-of-the-art bill of material (BoM), has a long term experience as automotive assembler for Infineon and is TS16949 certified and Infineon robust and green qualified. We are able to improve MSL capability from MSL3 to MSL2a. There is no change in form, fit and function, quality or reliability. The device dimensions will remain unchanged. Wafer fab and wafer test in KULIM are qualified for similar products in the same technology already. The final test location will remain unchanged at Infineon.

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► **Attachments:**

1_cip14058_a List of affected products

► **Time Schedule:**

■ Final qualification report:	Available
■ First samples available:	Available
■ Intended start of delivery:	01-January-2017 or earlier after customer release

Refer to page 4/4:

■ Last order date of unchanged product:	31-December-2016
■ Last delivery date of unchanged product:	30-June-2017

If you have any questions, please do not hesitate to contact your local Sales office.

PRODUCT REPLACEMENT



referring to PCN N° 2014-058-A

■ Last order date of unchanged product:	2016-12-31
■ Last delivery date of unchanged product:	2017-06-30

CURRENT				NEW (REPLACEMENT)			
Device	Ordering Code	OPN	Package	Device	Ordering Code	OPN	Package
TLE4263GS	SP000306724	TLE4263GSXUMA1	PG-DSO-8	TLE4263GS	SP001588902	TLE4268GSXUMA2	PG-DSO-8
TLE4268GS	SP000306725	TLE4268GSXUMA1	PG-DSO-8	TLE4268GS	SP001362942	TLE4268GSXUMA2	PG-DSO-8
TLE4269G	SP000300944	TLE4269GXUMA1	PG-DSO-8	TLE4269G	SP001588910	TLE4269GXUMA2	PG-DSO-8
TLE42694G	SP000317802	TLE42694GXUMA1	PG-DSO-8	TLE42694G	SP001362944	TLE42694GXUMA2	PG-DSO-8
TLE4279G	SP000306727	TLE4279GXUMA1	PG-DSO-8	TLE4279G	SP001588914	TLE4279GXUMA2	PG-DSO-8
TLE42794G	SP000358646	TLE42794GXUMA1	PG-DSO-8	TLE42794G	SP001362946	TLE42794GXUMA2	PG-DSO-8
TLE42994G	SP000253851	TLE42994GXUMA1	PG-DSO-8	TLE42994G	SP001428744	TLE42994GXUMA3	PG-DSO-8
TLE6251D	SP000836844	TLE6251DXUMA1	PG-DSO-8	TLE6251D	SP001363012	TLE6251DXUMA2	PG-DSO-8
TLE6251DS	SP000294173	TLE6251DSXUMA1	PG-DSO-8	TLE6251DS	SP001363014	TLE6251DSXUMA2	PG-DSO-8
TLE7250G	SP000735846	TLE7250GXUMA1	PG-DSO-8	TLE7250G	SP001363018	TLE7250GXUMA2	PG-DSO-8
TLE7250GVIO	SP000735852	TLE7250GVIOXUMA1	PG-DSO-8	TLE7250GVIO	SP001363016	TLE7250GVIOXUMA2	PG-DSO-8
TLE7259-2GE	SP000299877	TLE72592GEXUMA1	PG-DSO-8	TLE7259-2GE	SP001428746	TLE72592GEXUMA4	PG-DSO-8
TLE7259-3GE	SP001102542	TLE72593GEXUMA1	PG-DSO-8	TLE7259-3GE	SP001428748	TLE72593GEXUMA3	PG-DSO-8
TLE8250G	SP000551642	TLE8250GXUMA1	PG-DSO-8	TLE8250G	SP001428740	TLE8250GXUMA5	PG-DSO-8
TLE8250GVIO	SP000691818	TLE8250GVIOXUMA1	PG-DSO-8	TLE8250GVIO	SP001428742	TLE8250GVIOXUMA5	PG-DSO-8